



3.3V CMOS OCTAL BUS TRANSCIVER AND REGISTER WITH 3-STATE OUTPUTS AND 5 VOLT TOLERANT I/O

IDT74LVC652A

FEATURES:

- 0.5 MICRON CMOS Technology
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- $V_{CC} = 3.3V \pm 0.3V$, Normal Range
- $V_{CC} = 2.7V$ to $3.6V$, Extended Range
- CMOS power levels ($0.4\mu W$ typ. static)
- Rail-to-rail output swing for increased noise margin
- All inputs, outputs, and I/O are 5V tolerant
- Supports hot insertion
- Available in SOIC, SSOP, QSOP, and TSSOP packages

DRIVE FEATURES:

- High Output Drivers: $\pm 24mA$
- Reduced system switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

DESCRIPTION:

The LVC652A octal bus transceiver/register is built using advanced dual metal CMOS technology. The device consists of a bus transceiver circuit, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers.

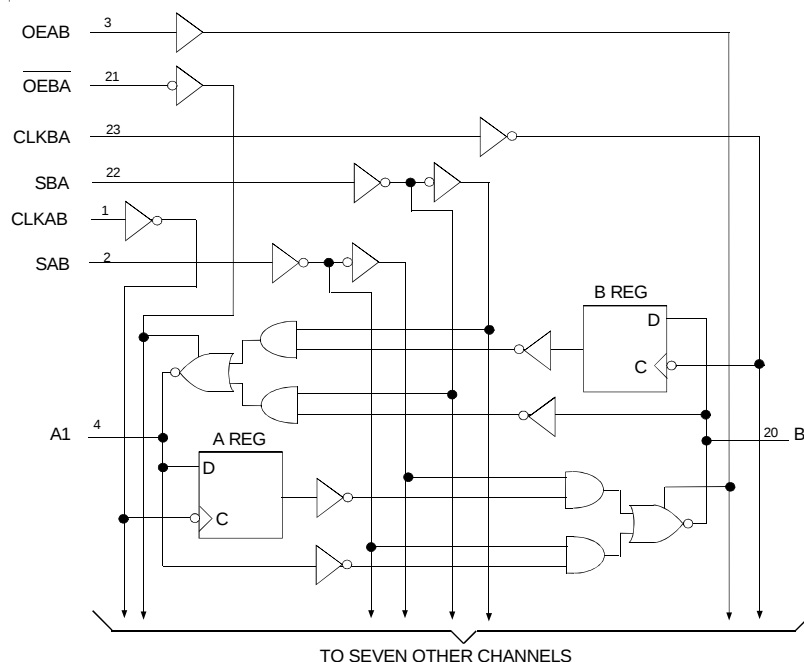
Output-enable (OEAB and $\overline{OEBA}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data.

Data on the A or B data bus, or both, is stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control pins. When the SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{OEBA}$. In this configuration, each output reinforces its input.

The LVC652A has been designed with a $\pm 24mA$ output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

Inputs can be driven from either 3.3V or 5V devices. This feature allows the use of this device as a translator in a mixed 3.3V/5V system environment.

FUNCTIONAL BLOCK DIAGRAM

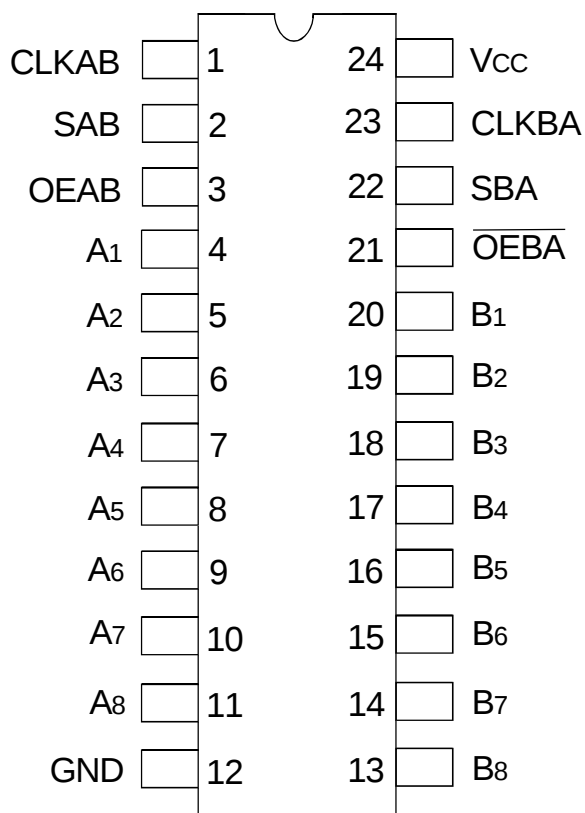


The IDT logo is a registered trademark of Integrated Device Technology, Inc.

INDUSTRIAL TEMPERATURE RANGE

APRIL 1999

PIN CONFIGURATION



SOIC/ SSOP/ QSOP/ TSSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
V _{TERM}	Terminal Voltage with Respect to GND	−0.5 to +6.5	V
T _{STG}	Storage Temperature	−65 to +150	°C
I _{OUT}	DC Output Current	−50 to +50	mA
I _{IK} I _{OK}	Continuous Clamp Current, V _I < 0 or V _O < 0	−50	mA
I _{CC} I _{SS}	Continuous Current through each V _{CC} or GND	±100	mA

NOTE:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

CAPACITANCE (T_A = +25°C, F = 1.0MHz)

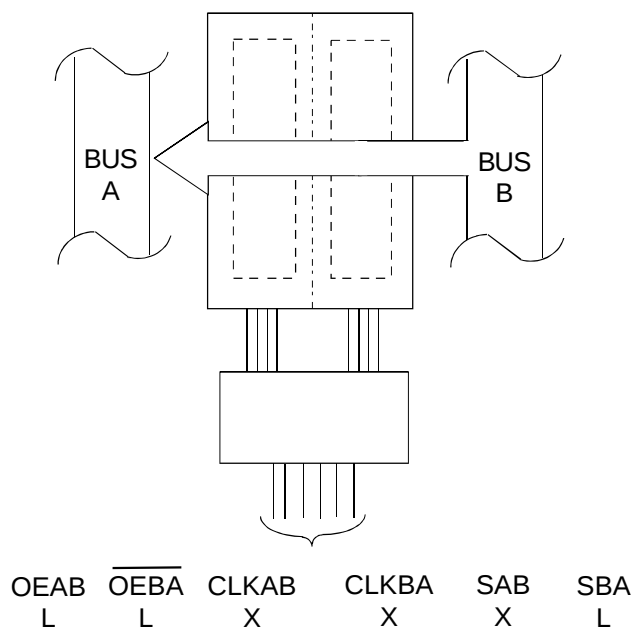
Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	4.5	6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	5.5	8	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	6.5	8	pF

NOTE:

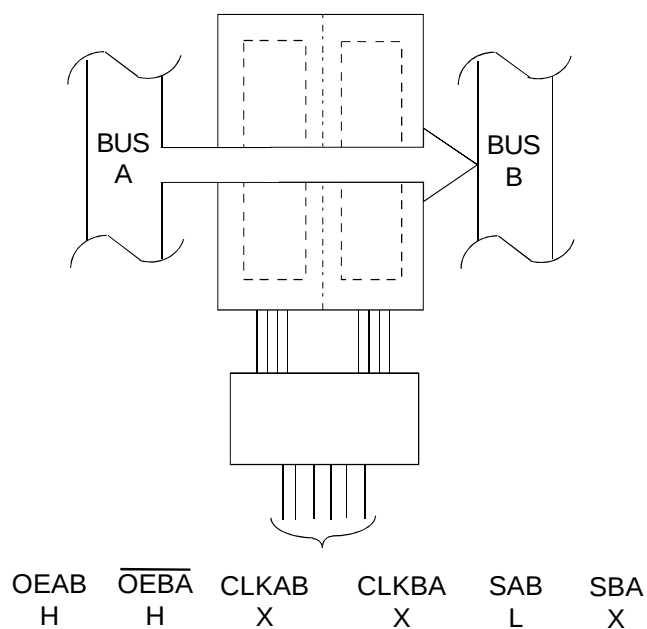
- As applicable to the device type.

PIN DESCRIPTION

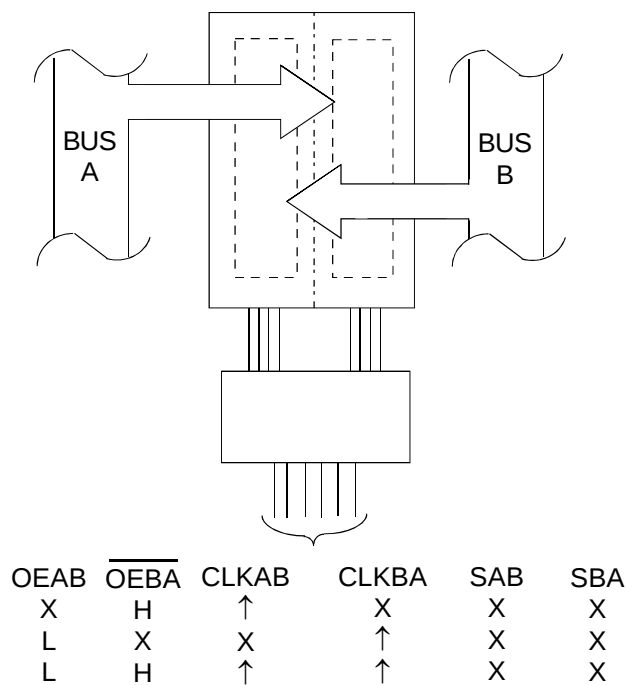
Pin Names	Description
A x	Data Register A Inputs Data Register B Outputs
B x	Data Register B Inputs Data Register A Outputs
CLKAB, CLKBA	Clock Pulse Inputs
SAB, SBA	Output Data Source Select Inputs
OEAB, $\overline{OEBA}$	Output Enable Inputs



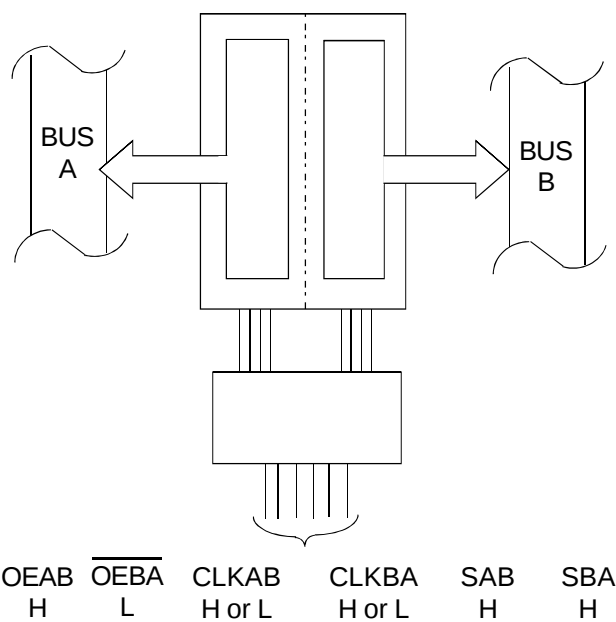
REAL-TIME TRANSFER BUS B TO BUS A



REAL-TIME TRANSFER BUS A TO BUS B



STORAGE FROM A, B, OR A AND B



TRANSFER STORED DATA TO A AND/OR B

FUNCTION TABLE⁽¹⁾

Inputs						Data I/O ⁽³⁾		Operation or Function
OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA	Ax	Bx	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X			Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified ⁽²⁾	Store A, Hold B
H	H	↑	↑	X ⁽²⁾	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified ⁽²⁾	Input	Store B, Hold A
L	L	↑	↑	X	X ⁽²⁾	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real time B data to A bus
L	L	X	H or L	X	H			Store B data to A bus
H	H	X	X	L	X	Input	Output	Real time A data to B bus
H	H	H or L	X	H	X			Store A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Store A data to B bus and Store B data to A bus

NOTES:

- H = HIGH Voltage Level
X = Don't Care
L = LOW Voltage Level
↑ = LOW-to-HIGH transition
- Select Control = L: clocks can occur simultaneously.
Select Control = H: clocks can be staggered to load both registers.
- The data output functions may be enabled or disabled by various signals at the OEAB or $\overline{\text{OEBA}}$ inputs. Data input functions are always enabled, i.e. data at the bus pins will be stored on every LOW-to-HIGH transition of the clock inputs.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = -40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
V _{IH}	Input HIGH Voltage Level	V _{CC} = 2.3V to 2.7V		1.7	—	—	V
		V _{CC} = 2.7V to 3.6V		2	—	—	
V _{IL}	Input LOW Voltage Level	V _{CC} = 2.3V to 2.7V		—	—	0.7	V
		V _{CC} = 2.7V to 3.6V		—	—	0.8	
I _{IH} I _{IL}	Input Leakage Current	V _{CC} = 3.6V	V _I = 0 to 5.5V	—	—	±5	μA
I _{OZH} I _{OZL}	High Impedance Output Current (3-State Output pins)	V _{CC} = 3.6V	V _O = 0 to 5.5V	—	—	±10	μA
I _{OFF}	Input/Output Power Off Leakage	V _{CC} = 0V, V _{IN} or V _O ≤ 5.5V		—	—	±50	μA
V _{IK}	Clamp Diode Voltage	V _{CC} = 2.3V, I _{IN} = -18mA		—	-0.7	-1.2	V
V _H	Input Hysteresis	V _{CC} = 3.3V		—	100	—	mV
I _{CC} I _{CH} I _{CCZ}	Quiescent Power Supply Current	V _{CC} = 3.6V	V _{IN} = GND or V _{CC}	—	—	10	μA
			3.6 ≤ V _{IN} ≤ 5.5V ⁽²⁾	—	—	10	
ΔI _{CC}	Quiescent Power Supply Current Variation	One input at V _{CC} - 0.6V, other inputs at V _{CC} or GND		—	—	500	μA

NOTES:

- Typical values are at V_{CC} = 3.3V, +25°C ambient.
- This applies in the disabled state only.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	VCC = 2.3V to 3.6V	IOH = - 0.1mA	VCC - 0.2	—	V
		VCC = 2.3V	IOH = - 6mA	2	—	
		VCC = 2.3V	IOH = - 12mA	1.7	—	
		VCC = 2.7V		2.2	—	
		VCC = 3V		2.4	—	
		VCC = 3V	IOH = - 24mA	2.2	—	
VOL	Output LOW Voltage	VCC = 2.3V to 3.6V	IoL = 0.1mA	—	0.2	V
		VCC = 2.3V	IoL = 6mA	—	0.4	
			IoL = 12mA	—	0.7	
		VCC = 2.7V	IoL = 12mA	—	0.4	
		VCC = 3V	IoL = 24mA	—	0.55	

NOTE:

1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate VCC range.
TA = - 40°C to + 85°C.

OPERATING CHARACTERISTICS, VCC = 3.3V ± 0.3V, TA = 25°C

Symbol	Parameter	Test Conditions	Typical	Unit
CPD	Power Dissipation Capacitance per Transceiver Outputs enabled	CL = 0pF, f = 10Mhz	84	pF
CPD	Power Dissipation Capacitance per Transceiver Outputs disabled		9.5	

SWITCHING CHARACTERISTICS⁽¹⁾

Symbol	Parameter	VCC = 2.7V		VCC = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	
fMAX		80	—	100	—	MHz
tPLH tPHL	Propagation Delay Ax to Bx or Bx to Ax	—	7.8	1.5	7.4	ns
tPLH tPHL	Propagation Delay CLKAB, CLKBA to Ax or Bx	—	8.4	1.5	8	ns
tPLH tPHL	Propagation Delay SBA or SAB to Ax or Bx	—	9.6	1.5	8.7	ns
tPZH tPZL	Output Enable Time OEBA to Ax	—	8.9	1.5	7.4	ns
tPHZ tPLZ	Output Disable Time OEBA to Ax	—	8.1	1.5	7.5	ns
tPZH tPZL	Output Enable Time OEAB to Bx	—	8.6	1.5	7.1	ns
tPHZ tPLZ	Output Disable Time OEAB to Bx	—	7.7	1.5	7.4	ns
tW	Pulse Duration CLKAB, CLKBA HIGH or LOW	3.3	—	3.3	—	ns
tSU	Set-up Time, data before CLKAB↑, CLKBA↑	1.9	—	1.9	—	ns
tH	Hold Time, data after CLKAB↑, CLKBA↑	1.5	—	1.7	—	ns
tsk(o)	Output Skew ⁽²⁾	—	—	—	500	ps

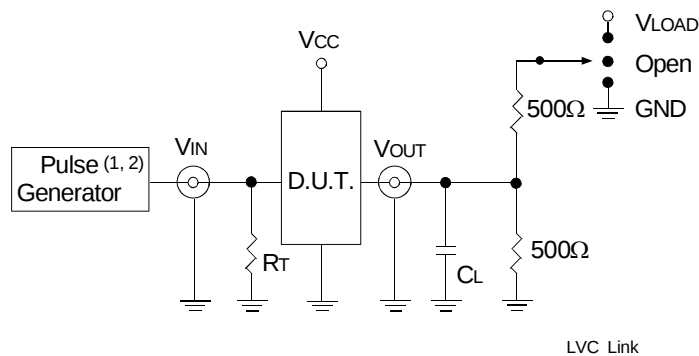
NOTES:

1. See TEST CIRCUITS AND WAVEFORMS. TA = - 40°C to + 85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	$V_{CC}^{(1)} = 3.3V \pm 0.3V$	$V_{CC}^{(1)} = 2.7V$	$V_{CC}^{(2)} = 2.5V \pm 0.2V$	Unit
V_{LOAD}	6	6	$2 \times V_{CC}$	V
V_{IH}	2.7	2.7	V_{CC}	V
V_T	1.5	1.5	$V_{CC} / 2$	V
V_{LZ}	300	300	150	mV
V_{HZ}	300	300	150	mV
C_L	50	50	30	pF



Test Circuit for All Outputs

DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

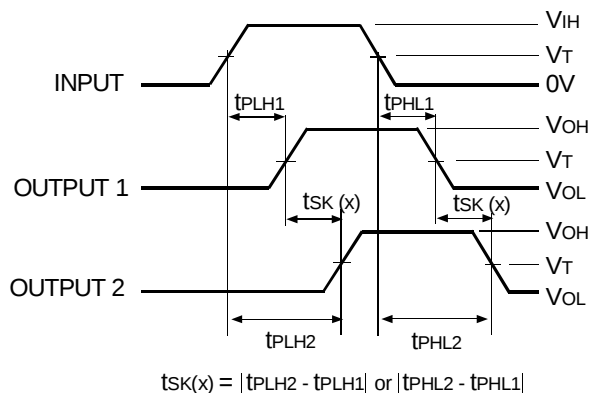
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

1. Pulse Generator for All Pulses: Rate $\leq 10\text{MHz}$; $t_r \leq 2.5\text{ns}$; $t_f \leq 2.5\text{ns}$.
2. Pulse Generator for All Pulses: Rate $\leq 10\text{MHz}$; $t_r \leq 2\text{ns}$; $t_f \leq 2\text{ns}$.

SWITCH POSITION

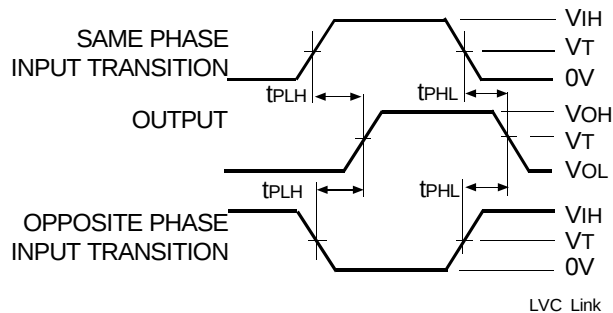
Test	Switch
Open Drain Disable Low Enable Low	V_{LOAD}
Disable High Enable High	GND
All Other Tests	Open



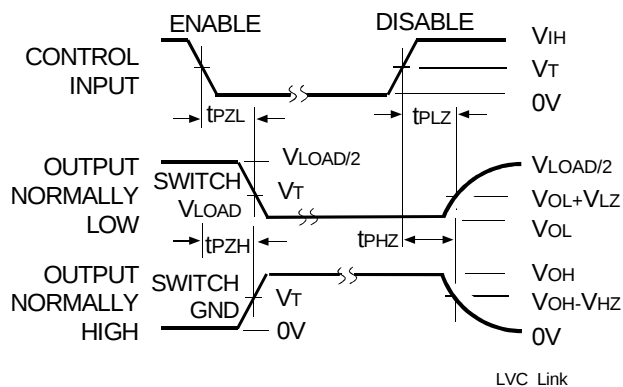
Output Skew - $ts_k(x)$

NOTES:

1. For $ts_k(o)$ OUTPUT1 and OUTPUT2 are any two outputs.
2. For $ts_k(b)$ OUTPUT1 and OUTPUT2 are in the same bank.



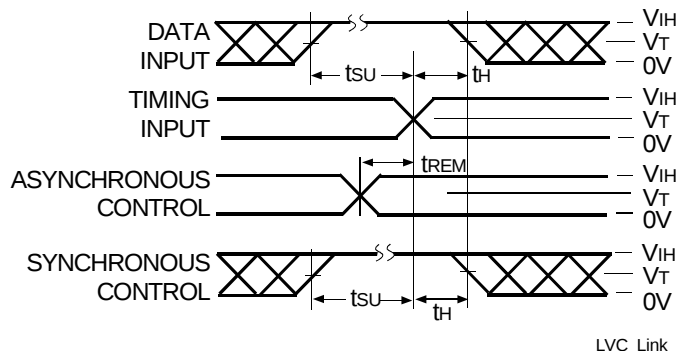
Propagation Delay



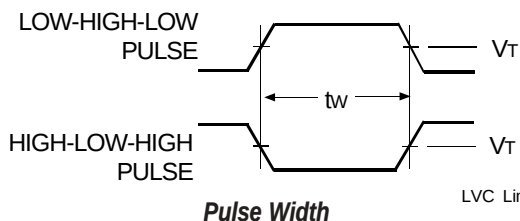
Enable and Disable Times

NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.



Set-up, Hold, and Release Times



Pulse Width

ORDERING INFORMATION

IDT	XX	LVC	X	XXXX	XX		
Temp. Range			Bus-Hold	Device Type	Package		
						SO	Small Outline IC (gull wing)
						PY	Shrink Small Outline Package
						Q	Quarter Size Small Outline Package
						PG	Thin Shrink Small Outline Package
				652A			Octal Bus Transceiver and Register with 3-State Outputs, $\pm 24\text{mA}$
				Blank			No Bus-hold
				74			-40°C to $+85^{\circ}\text{C}$



CORPORATE HEADQUARTERS
2975 Stender Way
Santa Clara, CA 95054

for SALES:
800-345-7015 or 408-727-6116
fax: 408-492-8674
www.idt.com

for Tech Support:
logichelp@idt.com
(408) 654-6459